



Amkor Announces US Advanced Packaging and Test Facility

Amkor enables a resilient domestic semiconductor supply chain with the construction of its new advanced packaging facility in Arizona

TEMPE, Ariz. -- November 30, 2023 -- Amkor Technology, Inc. (Nasdaq: AMKR), a leading provider of semiconductor packaging and test services, has announced its plan to build an advanced packaging and test facility in Peoria, Arizona. By the time of full project completion, Amkor projects to invest approximately \$2 billion and employ approximately 2,000 people at the new facility.

Amkor is the only US-headquartered OSAT (outsourced semiconductor assembly and test) service provider with advanced packaging technology capability and high-volume manufacturing experience. Upon completion, this will be the largest outsourced advanced packaging facility in the US.

"Expansion of a US semiconductor supply chain is underway, and as the largest US-headquartered advanced packaging company, we are excited to lead the charge in bolstering America's advanced packaging capabilities," said Giel Rutten, Amkor's president and chief executive officer. "Semiconductor companies, foundries, and other supply chain partners understand the need to strategically broaden their geographic footprint. The announcement of our new advanced packaging and test facility in Arizona is a clear signal of our intent to help our customers ensure resilient supply chains and be a part of a strong American semiconductor ecosystem."

In recent [Congressional testimony](#), Commerce Secretary Gina M. Raimondo highlighted advanced packaging as a major area of focus for the US government's effort to rebuild American semiconductor manufacturing. The Commerce Department made clear that developing robust advanced manufacturing capacity and capability is a key priority and essential to the success of the CHIPS program.

Amkor has secured approximately 55 acres of land with intent to build a state-of-the-art manufacturing campus with more than 500,000 square feet of clean room space. The first phase of the manufacturing plant is targeted to be ready for production within the next two to three years. Amkor plans to provide high volume, leading-edge technologies for advanced packaging and testing of semiconductors to support critical markets such as high-performance computing, automotive, and communications.

Amkor worked closely with Apple on the strategic vision and initial manufacturing capability of the Peoria facility, which will package and test chips produced for Apple at the nearby TSMC fab. When the new facility opens, Apple will be its first and largest customer.

Amkor first established its presence in the Greater Phoenix area in 1984 and is excited to expand its footprint in the evolving Arizona semiconductor industry. The new manufacturing location will uniquely position Amkor among a strong ecosystem of front-end fabs, IDMs, and suppliers with current or expanding presence in the area, including TSMC, Intel, Applied Materials, ASML and others.

The project has garnered strong support from the City of Peoria, the Arizona Commerce Authority, and government authorities as it expands the evolving semiconductor ecosystem, provides high-tech jobs, and increases economic energy in the Greater Phoenix metropolitan area.

To ensure the success of a project of this magnitude in the United States, Amkor has applied for CHIPS funding. The CHIPS and Science Act was established to boost US competitiveness, innovation, and national security in the semiconductor industry. As part of the \$52.7 billion program, the federal government will award \$39 billion to US companies in competitive grants to manufacturers to finance construction,



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expansion, and modernization of facilities and equipment. These funds will be critical to Amkor's project moving forward.

"Amkor's \$2 billion project—one of the largest microchip investments announced in Arizona since the passage of the CHIPS Act last year—will create good-paying jobs, strengthen our local economy, and help protect our national security," Arizona Senator Mark Kelly said. "As one of the first advanced packaging facilities in the US, this is a huge step forward to reducing dependence on other countries in the microchip supply chain. When negotiating the CHIPS and Science Act, one of my top priorities was making sure companies like Amkor had the support needed to develop a resilient supply chain in places like Arizona that are leading the way in bringing microchip manufacturing back to America."

"Amkor's announcement is a historic step forward for Arizona that will bolster America's national security and build a more resilient supply chain, bring billions of dollars into our state, and create thousands of good-paying jobs for Arizona workers," said Governor Katie Hobbs. "With this project, one of the most significant investments in advanced packaging in America, Arizona will solidify itself as a world leader in the semiconductor industry. I was glad to meet with the Arizona Commerce Authority and Amkor leadership in South Korea to discuss future investments in Arizona and am proud to have them as a partner. Together, we'll continue to expand the semiconductor ecosystem and continue Arizona's long history of leadership in the advanced manufacturing sector."

"Amkor has been a strategic OSAT partner to TSMC for many years," said Dr. CC Wei, Chief Executive Officer of TSMC. "TSMC applauds Amkor for investing in the future of the semiconductor industry with us in Arizona. We share Amkor's excitement for its significant investment and the value this facility will bring to TSMC, our customers, and the ecosystem."

"Apple is committed to help build a new era of advanced manufacturing, right here in the US," said Jeff Williams, Apple chief operating officer. "Apple and Amkor have worked together for more than a decade packaging chips used extensively in all Apple products, and we are thrilled that this partnership will now deliver the largest OSAT advanced packaging facility in the United States."

"This new US facility, in combination with our advanced facilities spanning Asia and Europe, further strengthens our broad geographic footprint, supporting global but also enabling regional supply chains," added Rutten. "This investment will reinforce our leadership position in advanced packaging and test within the key markets we serve while solidifying our commitment to expanding US-based chip manufacturing."

About Amkor Technology, Inc.

Amkor Technology, Inc. is the world's largest US headquartered OSAT (outsourced semiconductor assembly and test) service provider. Since its founding in 1968, Amkor has pioneered the outsourcing of IC packaging and test services and is a strategic manufacturing partner for the world's leading semiconductor companies, foundries, and electronics OEMs. Amkor provides turnkey manufacturing services for the communication, automotive and industrial, computing, and consumer industries, including but not limited to smartphones, electric vehicles, data centers, artificial intelligence, and wearables. Amkor's operational base includes production facilities, research and development centers, and sales and support offices located in key electronics manufacturing regions in Asia, Europe, and the United States. For more information, visit amkor.com.

Forward-Looking Statement Disclaimer

This press release contains forward-looking statements within the meaning of the federal securities laws, including statements about the amount and timing of CHIPS funding and government support, the start of production in Arizona, the size, capability, output and other features and benefits of the facility, the amount of investment, the supply chain, job creation, our market position, and growth. You are cautioned not to place undue reliance on forward-looking statements. All forward-looking statements in this press release



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are made based on our current expectations, forecasts, estimates, and assumptions. Because such statements include risks and uncertainties, actual results may differ materially from those anticipated in such forward-looking statements. Risk factors that could affect the outcome of the events set forth in these statements include, but are not limited to, that there can be no assurance that the facility will be built on the timeline, at the cost or to the specifications expected or at all or that the facility will generate sales or other benefits of the type or amount expected or at all and other factors discussed in the company's reports filed with or furnished to the Securities and Exchange Commission. All forward-looking statements attributable to us or persons acting on our behalf are expressly qualified in their entirety by this cautionary statement. We assume no obligation to review or update any forward-looking statements to reflect events or circumstances occurring after the date of this press release except as may be required by applicable law.

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